

APPLICATION DATA SHEET

Electronic Version 0.0.11

Stylesheet Version: 1.0

Attorney Docket Number: 9223-US-PA

Publication Filing Type: new-utility

Application Type: utility

Title of Invention: FLIP-CHIP PACKAGE SUBSTRATE AND FLIP CHIP DIE

Customer Number Attorney: 31561



Customer Number Correspondence Address: 31561



Foreign Priority:

91208321

TW

2002-06-05

Priority Claimed

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